

## DATA SHEET

## HM 65770

# 4 K x 4

## HIGH SPEED CMOS SRAM

### WITH OUTPUT ENABLE

## FEATURES

- **FAST ACCESS TIME**  
MILITARY : 25/35/45 ns (max)  
COMMERCIAL : 20/25/35/45 ns (max)
- **LOW POWER CONSUMPTION**  
ACTIVE : 385 mW (max)  
STANDBY : 27.5 mW (max)
- **WIDE TEMPERATURE RANGE :**  
- 55°C TO + 125°C
- **300 MILS WIDTH PACKAGE**
- **TTL COMPATIBLE INPUTS AND OUTPUTS**
- **ASYNCHRONOUS**
- **CAPABLE OF WITHSTANDING GREATER THAN 2000 V ELECTROSTATIC DISCHARGE**
- **SINGLE 5 VOLT SUPPLY**
- **OUTPUT ENABLE**

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## DESCRIPTION

The HM 65770 is a high speed CMOS static RAM organized as 4096 x 4 bits. It is manufactured using MHS's high performance CMOS technology. Access times as fast as 15 ns are available with maximum power consumption of only 385 mW. The HM 65770 features fully static operation requiring no external clocks or timing strobes. The automatic power-down feature reduces the power consumption by 90 % when the circuit is deselected.

Easy memory expansion is provided by an active low chip select (CS), an active low output enable (OE) and three state drivers.

All inputs and outputs of the HM 65770 are TTL compatible and operate from single 5 V supply thus simplifying system design.

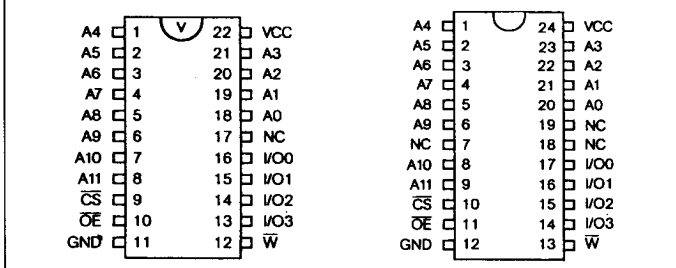
The HM-65770 is processed following the test methods of MIL STD 883C.

## PACKAGES

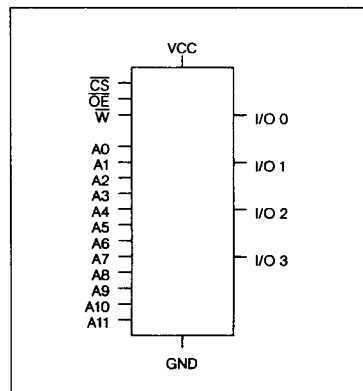
Plastic 300 mils, 22 pins, DIL.  
Ceramic 300 mils, 22 pins, DIL.

SO 300 mils, 24 pins, DIL.

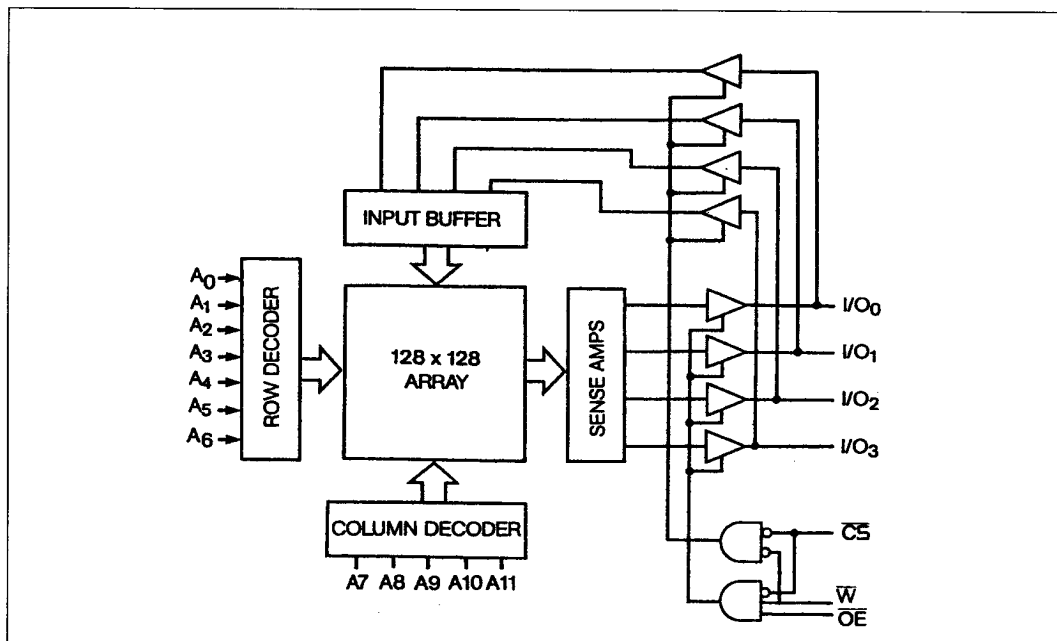
Pinout DIL 22/24 pins (top view)



## LOGIC SYMBOL



## BLOCK DIAGRAM



## PIN NAMES

|                          |                                 |
|--------------------------|---------------------------------|
| A0-A11 : Address inputs  | $\overline{CS}$ : Chip Select   |
| I/O0-I/O3 : Input/Output | $\overline{W}$ : Write enable   |
| Vcc : Power              | $\overline{OE}$ : Output enable |
| Gnd : Ground             |                                 |

## TRUTH TABLE

| $\overline{CS}$ | $\overline{OE}$ | $\overline{W}$ | DATA-IN | DATA-OUT | MODE     |
|-----------------|-----------------|----------------|---------|----------|----------|
| H               | X               | X              | Z       | Z        | Deselect |
| L               | L               | H              | Z       | Valid    | Read     |
| L               | H               | L              | Valid   | Z        | Write    |
| L               | L               | L              | Valid   | Z        | Write    |

L = low, H = high, X = H or L, Z = high impedance.

**ABSOLUTE MAXIMUM RATINGS**

Supply voltage to GND potential :  $-0.5\text{ V to }+7.0\text{ V}$   
 DC input voltage :  $-3.0\text{ V to }7.0\text{ V}$   
 DC output voltage in high Z state :  $-0.5\text{ V to }+7.0\text{ V}$

Storage temperature :  $-65^{\circ}\text{C to }+150^{\circ}\text{C}$   
 Output current into outputs (low) :  $20\text{ mA}$

**OPERATING RANGE**

|            |       | OPERATING VOLTAGE     | OPERATING TEMPERATURE                         |
|------------|-------|-----------------------|-----------------------------------------------|
| Military   | (- 2) | $5\text{ V} \pm 10\%$ | $-55^{\circ}\text{C to }+125^{\circ}\text{C}$ |
| Commercial | (- 5) | $5\text{ V} \pm 10\%$ | $0^{\circ}\text{C to }+70^{\circ}\text{C}$    |

**RECOMMENDED DC OPERATING CONDITIONS**

| PARAMETER | DESCRIPTION        | MINIMUM | TYPICAL | MAXIMUM | UNIT |
|-----------|--------------------|---------|---------|---------|------|
| Vcc       | Supply voltage     | 4.5     | 5.0     | 5.5     | V    |
| Gnd       | Ground             | 0.0     | 0.0     | 0.0     | V    |
| VIL       | Input low voltage  | $-3.0$  | 0.0     | 0.8     | V    |
| VIH       | Input high voltage | 2.0     | —       | VCC     | V    |

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**CAPACITANCE**

| PARAMETER | DESCRIPTION        | MINIMUM | TYPICAL | MAXIMUM | UNIT |
|-----------|--------------------|---------|---------|---------|------|
| Cin (1)   | Input capacitance  | —       | —       | 4       | pF   |
| Cout (1)  | Output capacitance | —       | —       | 7       | pF   |

Note : 1. TA =  $25^{\circ}\text{C}$  - f =  $1\text{ MHz}$  - Vcc =  $5.0\text{ V}$ . These parameters are not 100 % tested.

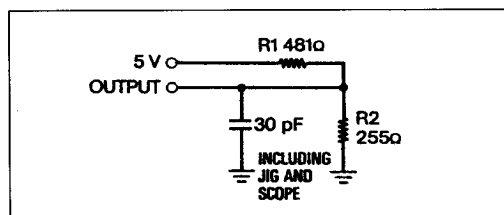
**AC TEST LOADS WAVEFORMS**

Fig. 1a.

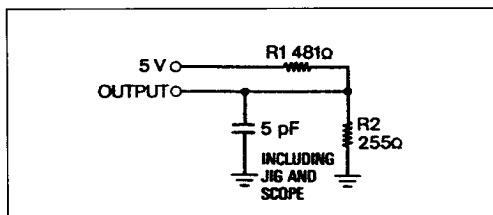


Fig. 1b.

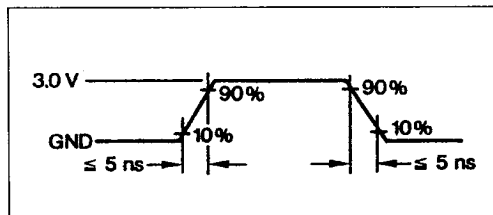
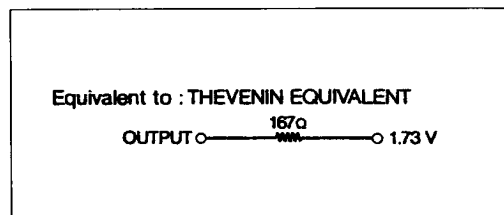


Fig. 2.

**ELECTRICAL CHARACTERISTICS DC PARAMETER**

| PARAMETER |     | DESCRIPTION                  | MINIMUM | TYPICAL | MAXIMUM | UNIT    |
|-----------|-----|------------------------------|---------|---------|---------|---------|
| IIX       | (2) | Input leakage current        | - 10.0  | -       | 10.0    | $\mu$ A |
| IOZ       | (3) | Output leakage current       | - 50.0  | -       | 50.0    | $\mu$ A |
| IOS       | (3) | Output short circuit current | -       | -       | - 350.0 | mA      |
| VOL       | (4) | Output low voltage           | -       | -       | 0.4     | V       |
| VOH       | (5) | Output high voltage          | 2.4     | -       | -       | V       |

- Notes :**
2.  $Gnd < V_{in} < V_{cc}$ ,  $Gnd < V_{out} < V_{cc}$  Output disabled.
  3.  $V_{cc} = \max$ ,  $V_{out} = Gnd$ , duration of the short circuit should not exceed 30 seconds.  
Not more than 1 output should be shorted at one time.
  4.  $V_{cc} \min$ ,  $I_{OL} = 8.0 \text{ mA}$ .
  5.  $V_{cc} \min$ ,  $I_{OH} = - 4.0 \text{ mA}$ .

**Consumption for Commercial specification :**

| SYMBOL    | PARAMETER                 | 65770<br>F-5 | 65770<br>H-5 | 65770<br>K-5 | 65770<br>M-5 | UNIT | VALUE |
|-----------|---------------------------|--------------|--------------|--------------|--------------|------|-------|
| ICCSB (6) | Standby supply current    | 20           | 20           | 20           | 20           | mA   | max   |
| ICCOP (7) | Dynamic operating current | 90           | 90           | 90           | 90           | mA   | max   |

**Consumption for Military specification :**

| SYMBOL    | PARAMETER                 | 65770<br>H-2 | 65772<br>K-2 | 65770<br>M-2 | UNIT | VALUE |
|-----------|---------------------------|--------------|--------------|--------------|------|-------|
| ICCSB (6) | Standby supply current    | 20           | 20           | 20           | mA   | max   |
| ICCOP (7) | Dynamic operating current | 120          | 120          | 120          | mA   | max   |

- Notes :**
6.  $\overline{CS} \geq V_{IH}$ , a pull-up resistor to  $V_{cc}$  on the  $\overline{CS}$  input is required to keep the device deselected during  $V_{cc}$  power-up otherwise ICCSB will exceed values given.
  7.  $V_{cc} \max$ , Output current = 0 mA,  $f = \max$ ,  $V_{in} = V_{cc}$  or Gnd.

## ELECTRICAL CHARACTERISTICS AC PARAMETERS

## AC CONDITIONS :

Input pulse levels : Gnd to 3.0 V  
 Input rise : 5 ns

Input timing reference levels : 1.5 V  
 Output loading IOL/IOH (see figure 1a and 1b) : + 30 pF

## WRITE CYCLE : Commercial specification

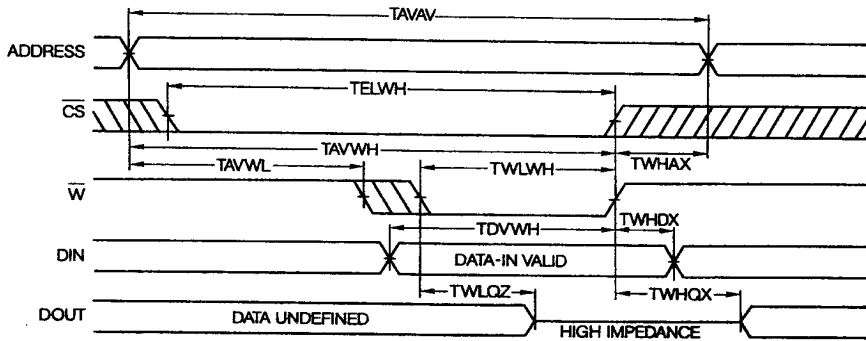
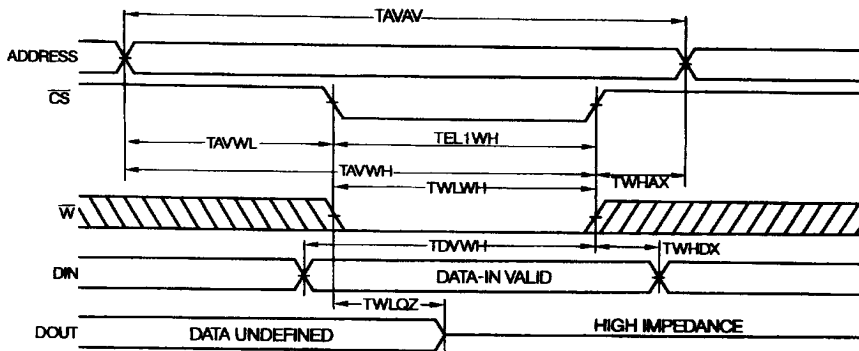
| SYMBOL    | PARAMETER                               | 65770<br>F-5 | 65770<br>H-5 | 65770<br>K-5 | 65770<br>M-5 | UNIT | VALUE |
|-----------|-----------------------------------------|--------------|--------------|--------------|--------------|------|-------|
| TAVAV     | Write cycle time                        | 20           | 25           | 35           | 45           | ns   | min   |
| TAVWL     | Address set-up time                     | 0            | 0            | 0            | 0            | ns   | min   |
| TAVWH     | Address valid to end of write           | 15           | 20           | 30           | 35           | ns   | min   |
| TDVWH     | Data set-up time                        | 10           | 10           | 15           | 15           | ns   | min   |
| TELWH     | $\overline{\text{CS}}$ low to write end | 15           | 20           | 35           | 35           | ns   | min   |
| TWLQZ (8) | Write low to high Z                     | 10           | 10           | 15           | 20           | ns   | max   |
| TWLWH     | Write pulse width                       | 15           | 20           | 30           | 35           | ns   | min   |
| TWHAX     | Address hold from end of write          | 0            | 0            | 0            | 0            | ns   | min   |
| TWHDX     | Data hold time                          | 0            | 0            | 0            | 3            | ns   | min   |
| TWHQX (8) | Write high to low Z                     | 3            | 6            | 6            | 6            | ns   | min   |

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## WRITE CYCLE : Military specification

| SYMBOL    | PARAMETER                               | 65770<br>H-2 | 65770<br>K-2 | 65770<br>M-2 | UNIT | VALUE |
|-----------|-----------------------------------------|--------------|--------------|--------------|------|-------|
| TAVAV     | Write cycle time                        | 25           | 35           | 40           | ns   | min   |
| TAVWL     | Address set-up time                     | 0            | 0            | 0            | ns   | min   |
| TAVWH     | Address valid to end of write           | 20           | 30           | 35           | ns   | min   |
| TDVWH     | Data set-up time                        | 10           | 15           | 15           | ns   | min   |
| TELWH     | $\overline{\text{CS}}$ low to write end | 25           | 30           | 35           | ns   | min   |
| TWLQZ (8) | Write low to high Z                     | 10           | 15           | 20           | ns   | max   |
| TWLWH     | Write pulse width                       | 20           | 30           | 35           | ns   | min   |
| TWHAX     | Address hold to end of write            | 0            | 0            | 0            | ns   | min   |
| TWHDX     | Data hold time                          | 0            | 0            | 3            | ns   | min   |
| TWHQX (8) | Write high to low Z                     | 6            | 6            | 6            | ns   | min   |

**Note :** 8. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

WRITE CYCLE 1 :  $\overline{W}$  Controlled (note 9)WRITE CYCLE 2  $\overline{CS}$  Controlled (note 9)

**Note :** 9. The internal write time of the memory is defined by the overlap of  $\overline{CS}$  LOW and  $\overline{W}$  LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input setup and hold timing should be referenced to the rising edge of the signal that terminates the write.

**READ CYCLE : Commercial specification**

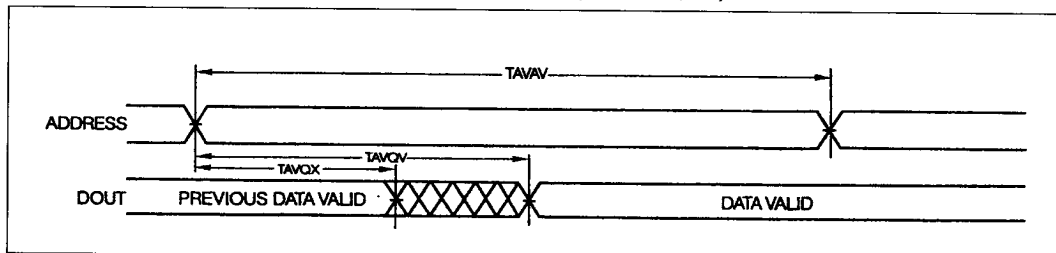
| SYMBOL | PARAMETER                          | 65770<br>F-5 | 65770<br>H-5 | 65770<br>K-5 | 65770<br>M-5 | UNIT | VALUE |
|--------|------------------------------------|--------------|--------------|--------------|--------------|------|-------|
| TAVAV  | Write cycle time                   | 20           | 25           | 35           | 45           | ns   | min   |
| TAVQV  | Address access time                | 20           | 25           | 35           | 45           | ns   | max   |
| TAVQX  | Address valid to low Z             | 2            | 3            | 3            | 3            | ns   | min   |
| TELQV  | Chip-select access time            | 15           | 15           | 25           | 30           | ns   | max   |
| TELQX  | $\overline{CS}$ low to low Z       | 3            | 3            | 5            | 5            | ns   | min   |
| TEHQZ  | $\overline{CS}$ high to high Z     | 15           | 15           | 20           | 25           | ns   | max   |
| TELIC  | $\overline{CS}$ low to power up    | 0            | 0            | 0            | 0            | ns   | min   |
| TEHICL | $\overline{CS}$ high to power down | 20           | 25           | 25           | 30           | ns   | max   |
| TGLQV  | Output Enable access time          | 12           | 15           | 15           | 20           | ns   | max   |
| TGLQX  | $\overline{OE}$ low to low Z       | 2            | 0            | 0            | 0            | ns   | min   |
| TGHQZ  | $\overline{OE}$ high to high Z     | 12           | 15           | 15           | 15           | ns   | max   |

**READ CYCLE : Military specification**

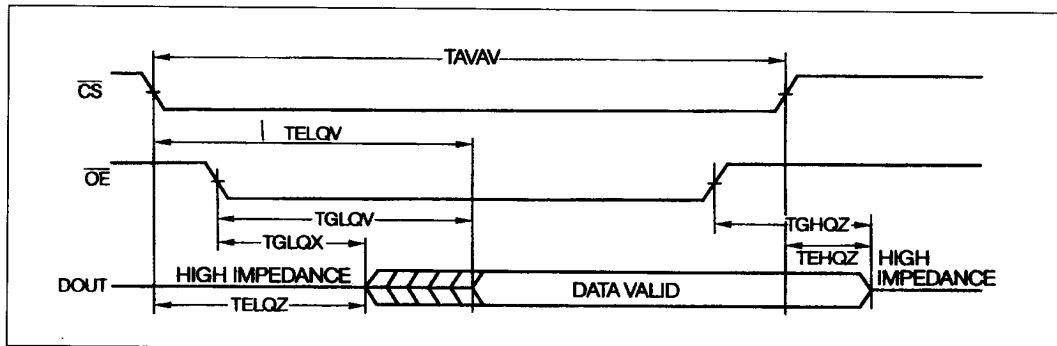
| SYMBOL | PARAMETER                          | 65770<br>H-2 | 65770<br>K-2 | 65770<br>M-2 | UNIT | VALUE |
|--------|------------------------------------|--------------|--------------|--------------|------|-------|
| TAVAV  | Read cycle time                    | 25           | 35           | 45           | ns   | min   |
| TAVQV  | Address access time                | 25           | 35           | 45           | ns   | max   |
| TAVQX  | Address valid to low Z             | 5            | 5            | 5            | ns   | min   |
| TELQV  | Chip-select access time            | 25           | 35           | 45           | ns   | max   |
| TELQX  | $\overline{CS}$ low to low Z       | 5            | 5            | 5            | ns   | min   |
| TEHQZ  | $\overline{CS}$ high to high Z     | 15           | 20           | 25           | ns   | max   |
| TELIC  | $\overline{CS}$ low to power up    | 0            | 0            | 0            | ns   | min   |
| TEHICL | $\overline{CS}$ high to power down | 20           | 25           | 30           | ns   | max   |
| TGLQV  | Output Enable access time          | 15           | 15           | 20           | ns   | max   |
| TGLQX  | $\overline{OE}$ low to low Z       | 0            | 0            | 0            | ns   | min   |
| TGHQZ  | $\overline{OE}$ high to high Z     | 15           | 15           | 20           | ns   | max   |

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## READ CYCLE nb 1 : (notes 10, 11)



## READ CYCLE nb 2 (notes 10, 12)



Notes : 10. W is HIGH for read cycle.

11. Device is continuously selected,  $\overline{CS} = V_{IL}$  and  $\overline{OE} = V_{IL}$ .

12. Address valid prior to or coincident with  $\overline{CS}$  transition LOW.

## ORDERING INFORMATION

| Package                                                                       | Device                                                 | Grade                                            | Level                                                                                                             |
|-------------------------------------------------------------------------------|--------------------------------------------------------|--------------------------------------------------|-------------------------------------------------------------------------------------------------------------------|
| HM1                                                                           | 65770                                                  | K                                                | - 5                                                                                                               |
| 0 - Chip form<br>1 - Ceramic 22 pins<br>3 - Plastic 22 pins<br>T - SO 24 pins | 4 k x 4 high speed<br>static RAM<br>with Output Enable | F = 20 ns<br>H = 25 ns<br>K = 35 ns<br>M = 45 ns | - 5 : Commercial<br>- 5+ : Commercial with B.I.<br>- 2 : Military<br>- 8 : Military with B.I.<br>(B.I. = Burn-in) |

## PACKAGE OUTLINE

For the packaging information, refer to chapter 10.

Package reference : Plastic DIL, 300 mils, 22 pins : X41  
Ceramic, 300 mils, 20 pins : C33  
SOIC DIL 300 mils, 24 pins : TBD.